| ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES® | omposition Dec<br>005. IPC, Bannockt<br>nd Pan-American co  | claration<br>ourn, Illinois. A<br>opyright conve | All rights reserved u ntions. | nder both | This docume<br>level parts, t                                      | ent is a declaration en declaration | on of the substan | ces within the m<br>ower level mater | nanufacturer l<br>rials for which | isted item. Note:<br>the manufacture | if the item is an a<br>er has engineering | ssembly with low responsibility. |  |
|---|---|--|-------------------------------|-----------|--|---|-------------------|--------------------------------------|-----------------------------------|--------------------------------------|---|----------------------------------|--|
|   | IPC Web Site for Information on IPC-1752 Standard Form Type |  |                               |           | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materi |   |                   |                                      | ous Materials                     | als and Mfg Information              |   |                                  |  |
| upplier Information                               |   |  |                               |           |  |   |                   |                                      |                                   |                                      |   |                                  |  |
| ompany name*                                      | Company unique ID   |  |                               | 1         | Unique ID Authority  |   |                   |                                      | Response Date*                    |                                      |   |                                  |  |
| nsemi   |   |  |                               |           |  |   |                   |                                      | 2024-04-17                        |                                      |   |                                  |  |
| Contact Name Title - Contact                      |   |  | Contact                       |           |  | Phone - Contact*  |                   |                                      |                                   | Email - Contact*                     |   |                                  |  |
| Product-Env-Stewards                              | Product Enviro Compliance                                   |  |                               |           | NA   |   |                   |                                      | Product-Env-Stewards@onsemi.com   |                                      |   |                                  |  |
| Authorized Representative* Title                  |   |  | Title - Representative        |           |  | Phone - Representative*   |                   |                                      | Eı                                | Email - Representative*              |   |                                  |  |
| roduct-Env-Stewards                               | Product Enviro Compliance                                   |  |                               |           | NA   |   |                   |                                      | Product-Env-Stewards@onsemi.com   |                                      |   |                                  |  |
| Requester Item Number                             | Requester Item Number Mfr Iten                              |  | n Number Mfr Item Name        |           |  | Effective Date  | Version           | Manufacturing Site                   |                                   | Weight*                              | UOM                                       | Unit Type                        |  |
|   | MBRF30  | MBRF30L60CTG 30A, 60V FP S                       |                               | THOTTKY   |  | 2024-04-17  |                   | KR8                                  |                                   | 1436.68                              | mg  | Each                             |  |
| Ianufacturing Proccess Info                       | ormation  |  |                               |           |  | •   |                   |                                      |                                   |                                      |   |                                  |  |
| Terminal Plating / Grid Arr                       | Terminal Plating / Grid Array Material Terminal Ba          |  | Alloy J-STD-020 MSL           |           | L Rating   | Peak Process Body Temperatu   |                   | ature Max Tim                        | ne at Peak Ter                    | nperature Num                        | ber of Reflow Cy                          | cles                             |  |
| Matte Tin (Sn) - annealed                         |   | CU Alloy NA                                      |                               |           | 0 C  |   | 30                |                                      | seconds 3                         |                                      |   |                                  |  |
| omments   |   |  |                               |           |  |   |                   |                                      |                                   |                                      |   |                                  |  |
|   |   |  |                               |           |  |   |                   |                                      |                                   |                                      |   |                                  |  |
| or more information regarding ma                  | terial composition  | please refer to                                  | page 3                        |           |  |   |                   |                                      |                                   |                                      |   |                                  |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *  | Detailed  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | (Pb), Mercury (Hg), Hexavalent Chro  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP). |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybromina<br>contains a RoHS restricted substance inexces<br>encompass all such components. Supplier cer<br>as of the date that Supplier completes this for<br>Company acknowledges that Supplier may h<br>independently verified information provided<br>certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip<br>s of an applicable quantity limit, please in<br>iffies that it gathered the information it pr<br>m.Supplier acknowledges that Company<br>ave relied on informationprovided by oth<br>by others, Supplier agrees that, at a minir<br>and the Supplier enter into a written agr<br>esource of the Supplier's liability and the | henyl ethers (each a "RoHS restricted substa<br>ndicate below which, if any, RoHS exemption<br>ovides in this form using appropriate methoo<br>will rely on this certification in determining<br>ers in completing this form, and that Supplie<br>num, itssuppliers have provided certification<br>eement with respect to the identified part, the<br>Company's remedies for issues that arise reg                               | nce") in exco<br>n you believe<br>ls to ensure i<br>the compliar<br>r may not ha<br>s regarding t<br>terms and co | e may apply. If the part is an assembly with low<br>s accuracy and that such information is true an<br>ce of its products with European Union member<br>de independently verified such information. Ho<br>neir contributions to the part, and those certifica | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>d correct to the best of its knowledge and belief,<br>er state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>ations are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 4 - Item(   | s) does not contain RoHS restricted subst  | ances per the definition above except for sele   | ected exempt  | ions Supplier Acceptance  | * Accepted  |  |  |  |  |  |  |
| Exemption: 7a: Lead in high melting temp   | erature type solders (i.e. lead based sol  | der alloys containing 85% by weight or m   | ore lead).  |   |   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.                        |  |  |   |   |   |  |  |  |  |  |  |
| Supplier Digital Signature   | astislav Drska   | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

|                      | cable [E] enter the weigh |                 |          | ance category (JIG or Requester) or enter<br>[F] Optionally enter the positive (+) and |                  |        |         |                 |
|----------------------|---------------------------|-----------------|----------|--|------------------|--------|---------|-----------------|
| Homogeneous Material | Weight                    | Unit of Measure | Level    | Substance  | CAS              | Exempt | Weight  | Unit of Measure |
| Die                  | 8.32                      | mg              | Supplier | Silicon (Si)   | 7440-21-3        |        | 8.32    | mg              |
| Die Attach           | 13.08                     | mg              | А        | Lead (Pb)  | 7439-92-1        | 7a     | 12.426  | mg              |
|                      |                           |                 | Supplier | Tin (Sn)   | 7440-31-5        |        | 0.654   | mg              |
| Lead Frame           | 498.3                     | mg              | Supplier | Copper (Cu)  | 7440-50-8        |        | 498.3   | mg              |
| Mold Compound-Black  | 897.4                     | mg              |          | Phenolic Resin   | proprietary data |        | 44.87   | mg              |
|                      |                           |                 | Supplier | Epoxy Phenol Resin   | Proprietary Data |        | 67.305  | mg              |
|                      |                           |                 | Supplier | Carbon Black (C)   | 1333-86-4        |        | 4.487   | mg              |
|                      |                           |                 | Supplier | Fused Silica (SiO2)  | 60676-86-0       |        | 197.428 | mg              |
|                      |                           |                 | Supplier | Silica Crystalline (SiO2)  | 14808-60-7       |        | 583.31  | mg              |
| Plating              | 12.24                     | mg              | Supplier | Tin (Sn)   | 7440-31-5        |        | 12.24   | mg              |
| Wire Bond - Al       | 7.34                      | mg              | Supplier | Aluminum (Al)  | 7429-90-5        |        | 7.34    | mg              |